United States Patent [19]

McCarthy

[11] **Des. 273,006**

[45] ** **Mar. 13, 1984**

[54] **TWIN HEAT SINK FOR ELECTRONIC SEMICONDUCTOR DEVICES**

[75] Inventor: **Alfred F. McCarthy,** Belmount, N.H.

[73] Assignee: **Aavid Engineering, Inc.,** Laconia, N.H.

[**] Term: **14 Years**

[21] Appl. No.: **252,029**

[22] Filed: **Apr. 8, 1981**

[52] **U.S. Cl.** **D13/23**

[58] **Field of Search** ..... D13/23; 174/16 HS; 357/81; 165/80, 80 A, 80 B

[56] **References Cited**

U.S. PATENT DOCUMENTS

3,407,868	10/1968	Coe	165/80 B
3,893,161	7/1975	Pesak, Jr.	357/81
4,012,769	3/1977	Edwards et al.	357/81
4,054,901	10/1977	Edwards et al.	357/81

OTHER PUBLICATIONS

Amperex Transistor brochure, 6/66, Extruded Aluminum Heat-Sink.

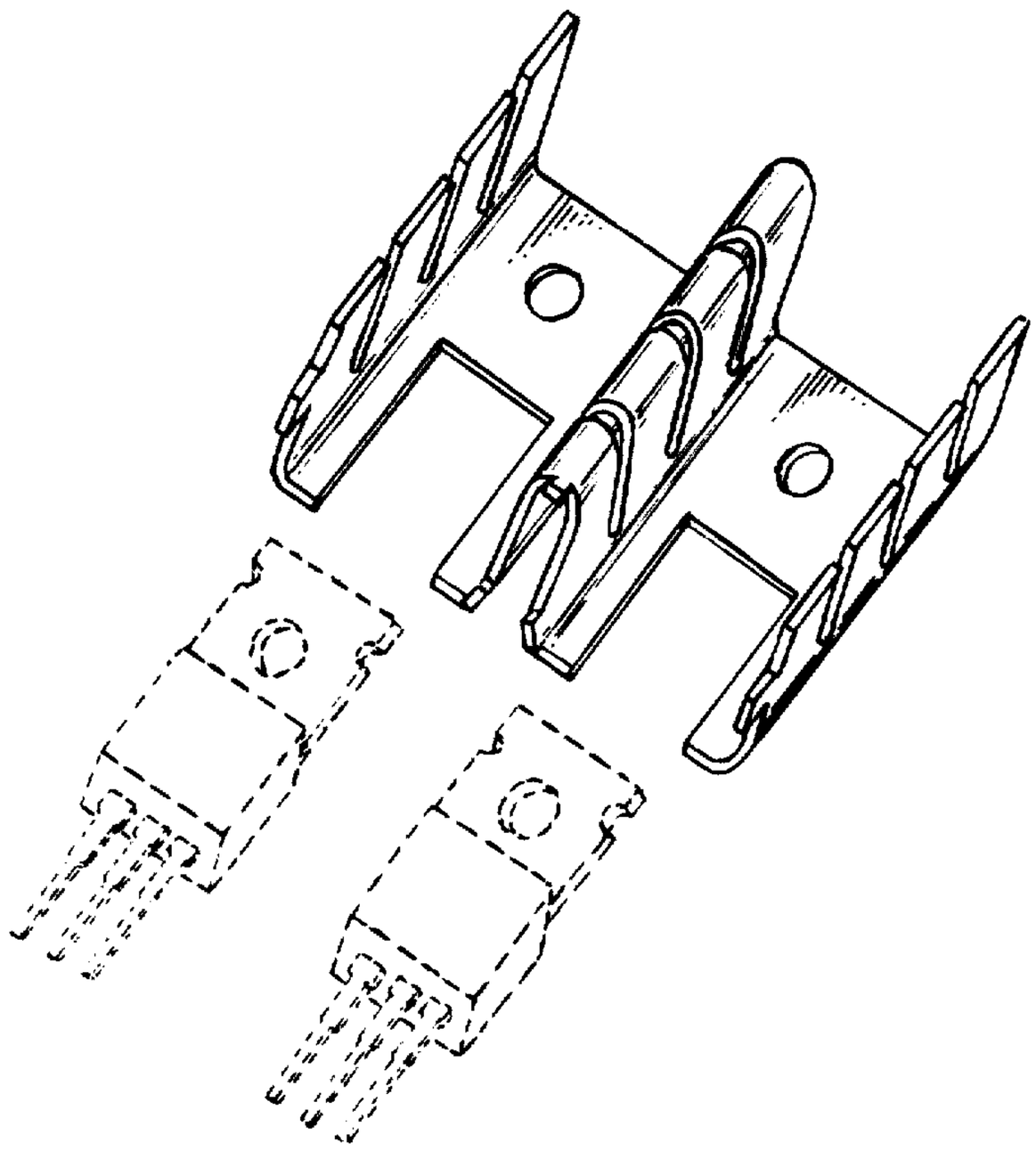
Primary Examiner—Susan J. Lucas
Attorney, Agent, or Firm—James E. Mrose

[57] **CLAIM**

The ornamental design for a twin heat sink for electronic semiconductor devices, substantially as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a twin heat sink for electronic semiconductor devices showing my new design; the broken lines being shown for illustrative purposes, only;
FIG. **2** is a front elevational view of the same heat sink;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a side elevational view thereof, looking toward the right side of the heat sink as it is shown in FIG. **1**;
FIG. **5** is a side elevational view thereof, looking toward the left side of the heat sink as it is shown in FIG. **1**;
FIG. **6** is a top plan view thereof; and
FIG. **7** is a bottom plan view thereof.



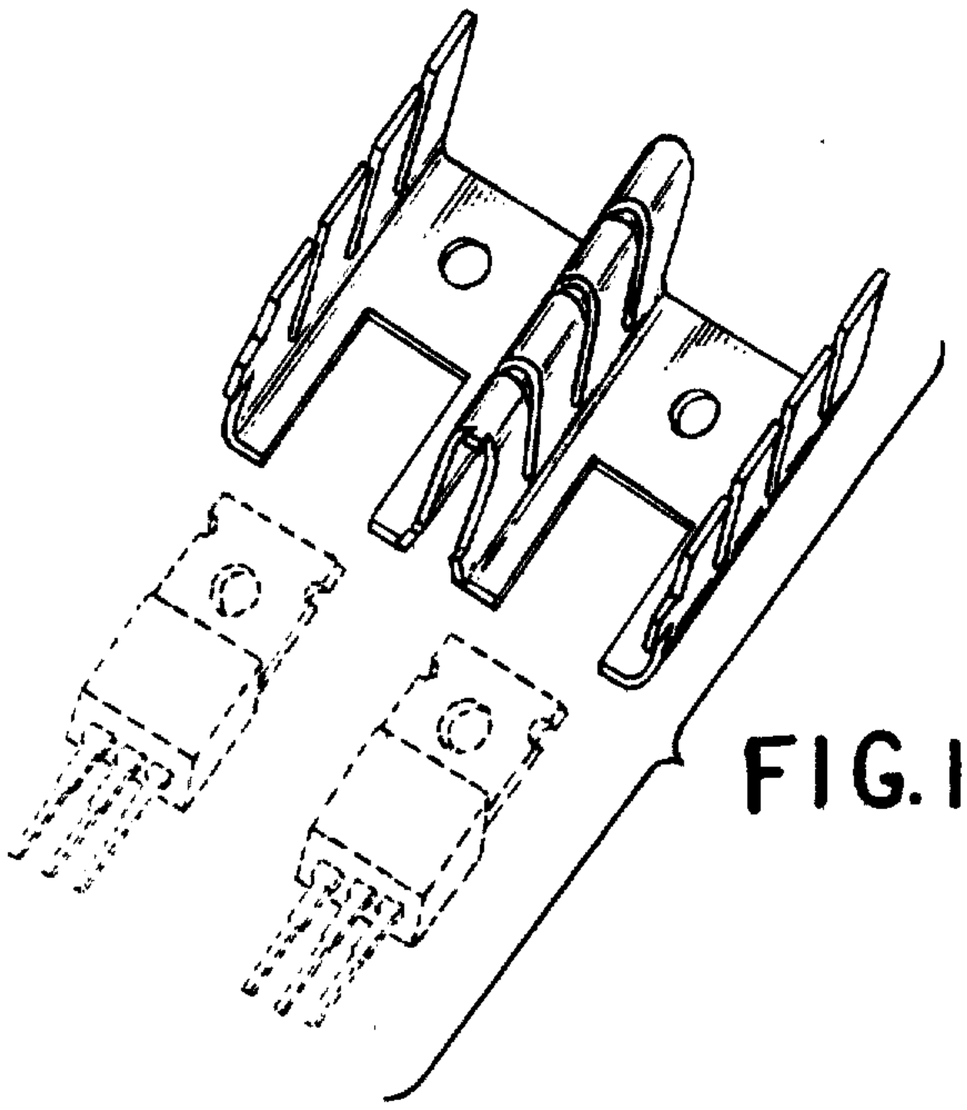


FIG. 1

FIG. 2

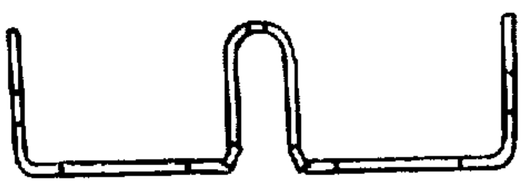


FIG. 3

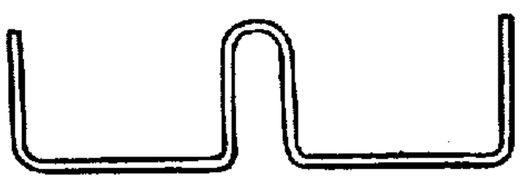


FIG. 4

FIG. 5

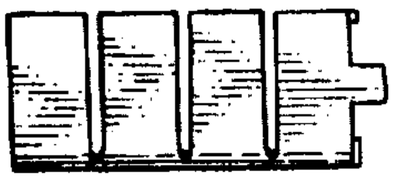


FIG. 6

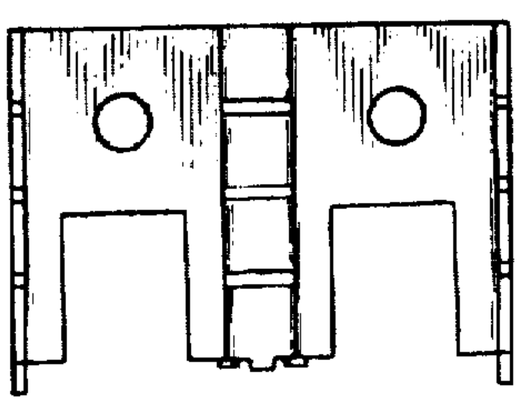


FIG. 7